

DESCRIPTION

The SPN1032 is the N-Channel enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance and provide superior switching performance. These devices are particularly suited for low voltage applications such as notebook computer power management and other battery powered circuits where high-side switching, low in-line power loss, and resistance to transients are needed.

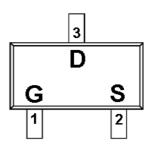
APPLICATIONS

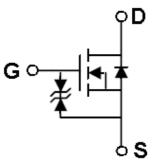
- Drivers : Relays/Solenoids/Lamps/Hammers
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers

FEATURES

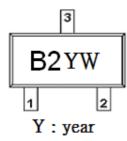
- □ N-Channel30V/0.95A,RDS(ON)=550mΩ@VGS=4.5V30V/0.75A,RDS(ON)=650mΩ@VGS=2.5V30V/0.65A,RDS(ON)=850mΩ@VGS=1.8V
- □ Super high density cell design for extremely low RDS (ON)
- ☐ Exceptional on-resistance and maximum DC current capability
- □ SOT-523 (SC-89-3L) package design

PIN CONFIGURATION(SOT-523/SC-89-3L)





PART MARKING



W: week

PIN DESCRIPTION					
Pin	Symbol	Description			
1	G	Gate			
2	S	Source			
3	D	Drain			

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN1032S52RG	SOT-523	B2
SPN1032S52RGB	SOT-523	B2

★ SPN1032S52RG: Tape Reel; Pb – Free

★ SPN1032S52RGB : Tape Reel ; Pb – Free, Halogen – Free

ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		VDSS	30	V
Gate –Source Voltage		VGSS	±12	V
Continuous Dusin Comment(Tr. 150°C)	Ta=25°C	In	1.2	A
Continuous Drain Current(T _J =150°C)	Ta=125°C	Id	1.0	
Pulsed Drain Current (*)		IDM	2.5	A
Thermal Resistance-Junction to Ambient		R _θ JA	375	°C/W
Power Dissipation	Ta=25°C	PD	1.35	W
Operating Junction Temperature		Тл	-55/150	$^{\circ}\!\mathbb{C}$
Storage Temperature Range		Tstg	-55/150	$^{\circ}\mathbb{C}$

(*) Pulse width limited by safe operating area

ELECTRICAL CHARACTERISTICS

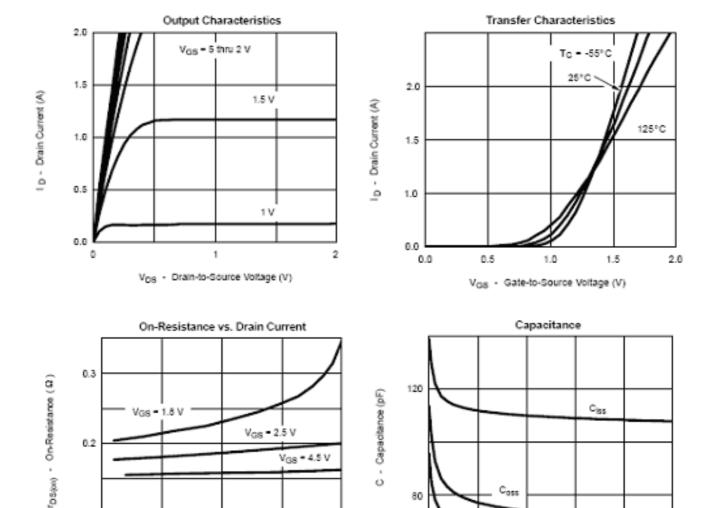
(Ta=25°C Unless otherwise noted)

Parameter	ameter Symbol Conditions		Min.	Тур	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V(BR)DSS VGS=0V,ID= 250uA		30			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	0.35		1.0] v	
Gate Leakage Current	Igss	$V_{DS}=0V,V_{GS}=\pm 12V$			±30	uA	
Zero Gate Voltage Drain Current	T	V _{DS} =24V,V _{GS} =0V,T _J =25°C			1	uA	
	IDSS	VDS=24V,VGS=0V,TJ=55°C			100		
On-State Drain Current	ID(on)	$V_{DS} \ge 4.5V, V_{GS} = 5V$	0.7			A	
		Vgs=4.5V,Id=0.95A		0.26	0.55	Ω	
Drain-Source On-Resistance	RDS(on)	Vgs=2.5V,Id=0.75A		0.38	0.65		
		Vgs=1.8V,Id=0.65A		0.52	0.85		
Forward Transconductance	gfs	Vds=10V,Id=0.4A		1.0		S	
Diode Forward Voltage	Vsd	Is=0.15A,VGS=0V		0.8	1.2	V	
Dynamic							
Total Gate Charge	Qg			1.2	1.5		
Gate-Source Charge	Qgs	$V_{DS}=10V, V_{GS}=4.5V,$ $I_{D}\equiv0.6A$		0.2		nC	
Gate-Drain Charge	Qgd	ID-0.0A		0.3			
Input Capacitance	Ciss			7.2			
Output Capacitance	Coss	$V_{DS} = 10V$, $f = 1$ MHz, V_{GS}		17		pF	
Reverse Transfer Capacitance	Crss	= 0V		1.6		r	
Turn-On Time	td(on)	$V_{DD}=10V,RL=10\Omega$,		5	10	ns	
Turn-On Time	tr	ID=0.5A VGEN=4.5V		8	15		
Turn-Off Time	td(off)	,RG=6Ω		10	18		
	tf			1.2	2.8		

TYPICAL CHARACTERISTICS

0.1

0.0



1.5

Ip - Drain Current (A)

2.0

80

Cras

Coss

12

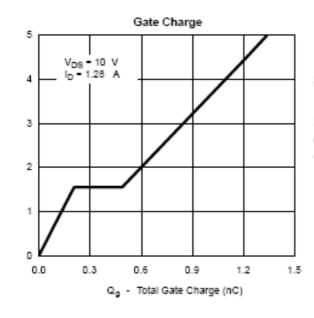
Vps - Drain-to-Source Voltage (V)

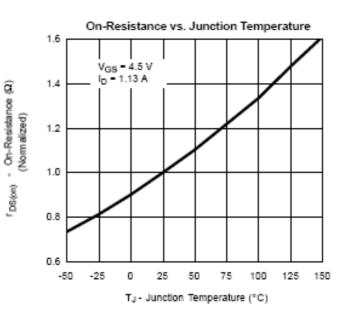
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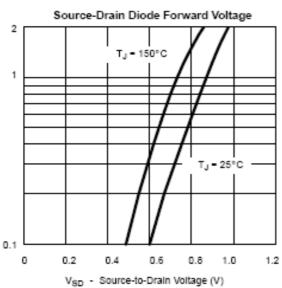
TYPICAL CHARACTERISTICS

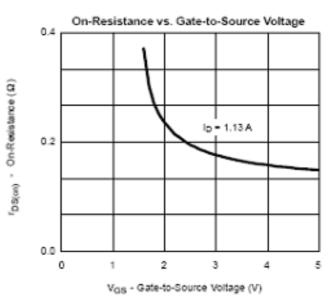
V_{GS} - Gate-to-Source Voltage (V)

Is - Source Current (A)



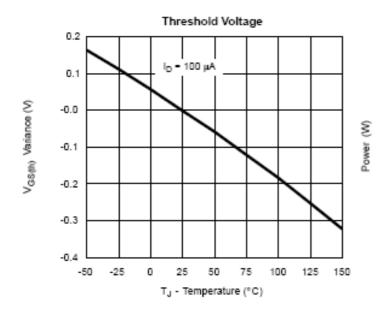


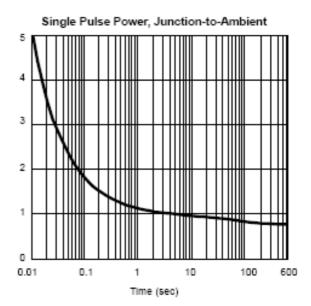




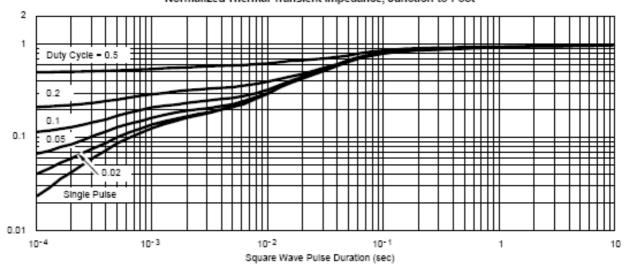
TYPICAL CHARACTERISTICS

Normalized Effective Transient Thermal Impedance



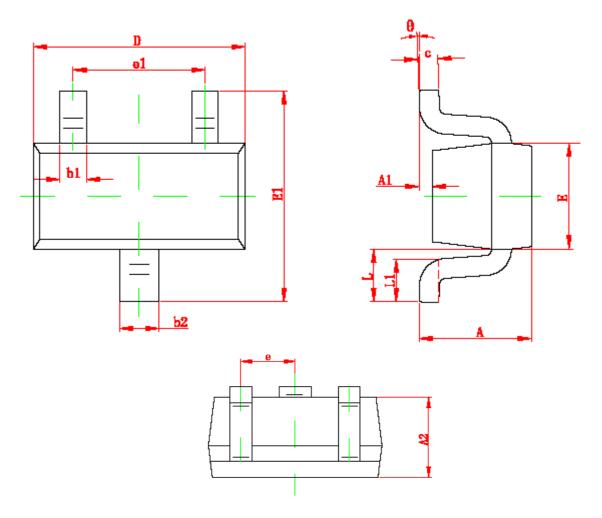


Normalized Thermal Transient Impedance, Junction-to-Foot





SOT-523 PACKAGE OUTLINE



C. mahad	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.700	0.900	0.028	0.035	
A1	0.000	0.100	0.000	0.004	
A2	0.700	0.800	0.028	0.031	
b1	0.150	0.250	0.006	0.010	
b2	0.250	0.325	0.010	0.013	
С	0.100	0.200	0.004	0.008	
D	1.500	1.700	0.059	0.067	
E	0.750	0.850	0.030	0.033	
E1	1.450	1.750	0.057	0.069	
е	0.500 TYP		0.020 TYP		
e1	0.900	1.100	0.035	0.043	
L	0.550 REF		0.022	REF	
L1	0.280	0.440	0.011	0.017	
θ	0°	4°	0°	4°	

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